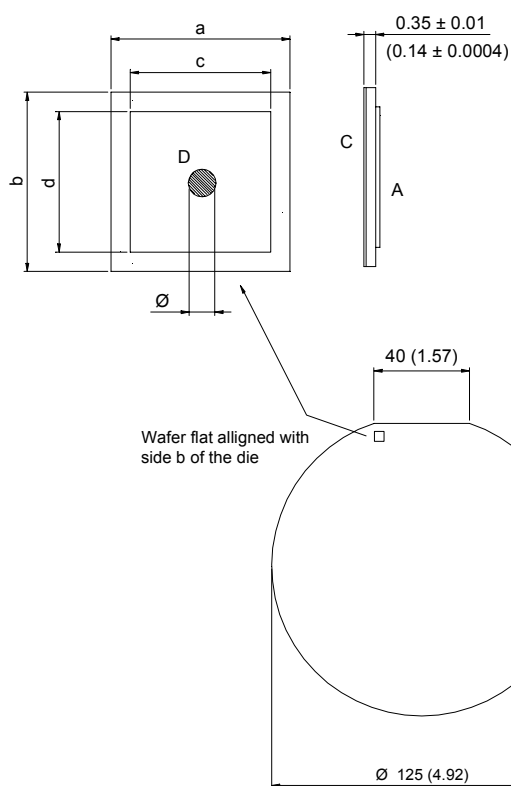


SCHOTTKY DIE 200 x 200 mils



NOTES:

1. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
2. CONTROLLING DIMENSION: (INCH).
3. DIMENSIONS AND TOLERANCES:
 - $a = 5.08 \pm 0, - 0.05$
($0.200 \pm 0, - 0.002$)
 - $b = 5.08 \pm 0, - 0.05$
($0.200 \pm 0, - 0.002$)
 - $c = 4.57 \pm 0, - 0.003$
($0.180 \pm 0, - 0.0001$)
 - $d = 4.57 \pm 0, - 0.003$
($0.180 \pm 0, - 0.0001$)
 - $\varnothing = 0.7 \pm 0.1$
(0.03 ± 0.004)
4. LETTER DESIGNATION:
 - A = Anode (Top Metal)
 - C = Cathode (Back Metal)
 - D = Reject Ink Dot (only on non-conforming dies)
5. SAWING:
 - Recommended Blade
 - SEMITEC S1025 QS00 Blade

NOT TO SCALE

NOTE: 10 mils die thickness is available on specific request only.
Contact factory for information.

Electrical Characteristics

Device #	T _J Max. (°C)	V _R (V)	Typ. I _R @ 25°C (μA)	Typ. I _R @ 125°C (mA)	Max. V _F @ I _F (V)	Package Style
SC200R015x5x	125	15	7500	900	0.45 @ 80A	D-61
SC200S020x5x	150	20	1200	450	0.51 @ 80A	D-61
SC200S030x5x	150	30	600	270	0.55 @ 80A	D-61
SC200S045x5x	150	45	400	210	0.66 @ 80A	D-61
SC200S060x5x	150	60	n.a. contact factory			
SC200H045x5x	175	45	70	26	0.74 @ 80A	D-61
SC200H100x5x	175	100	30	18	0.89 @ 60A	D-61
SC200H150x5x	175	150	15	10	1.14 @ 80A	D-61

Mechanical Data

Device #		Metal Thickness Front Metal			Metal Thickness Back Metal		
SC200xxxxA5x	Wire Bondable	–	Al 30 kÅ	–	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ
SC200xxxxS5x	Solderable	Ti 2 kÅ	Ni 1 kÅ	Ag 35 kÅ	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ

Recommended Storage Environment: Store in original container, in dessicated nitrogen, with no contamination.

Shelf life for parts stored in above condition is 2 years.

If the storage is done in normal atmosphere shelf life is reduced to six months.

Packaging

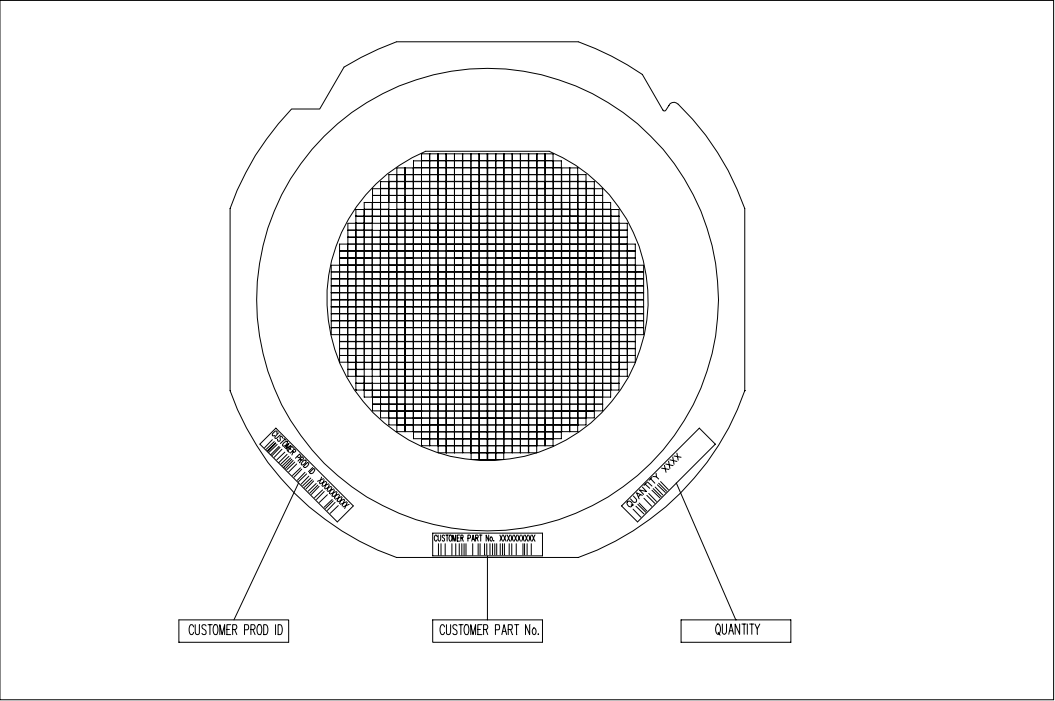
Device #	Description	Minimum Order Quantity Die in Sale Package
SC200xxxx5B	Inked Probed Unsawn Wafer (Wafer in Box)	350
SC200xxxx5R	Probed Die in Tape & Reel	8,000
SC200xxxx5P	Probed Die in Waffle Pack	350
SC200xxxx5F	Inked Probed Sawn Wafer on Film	350

Ordering Information Table

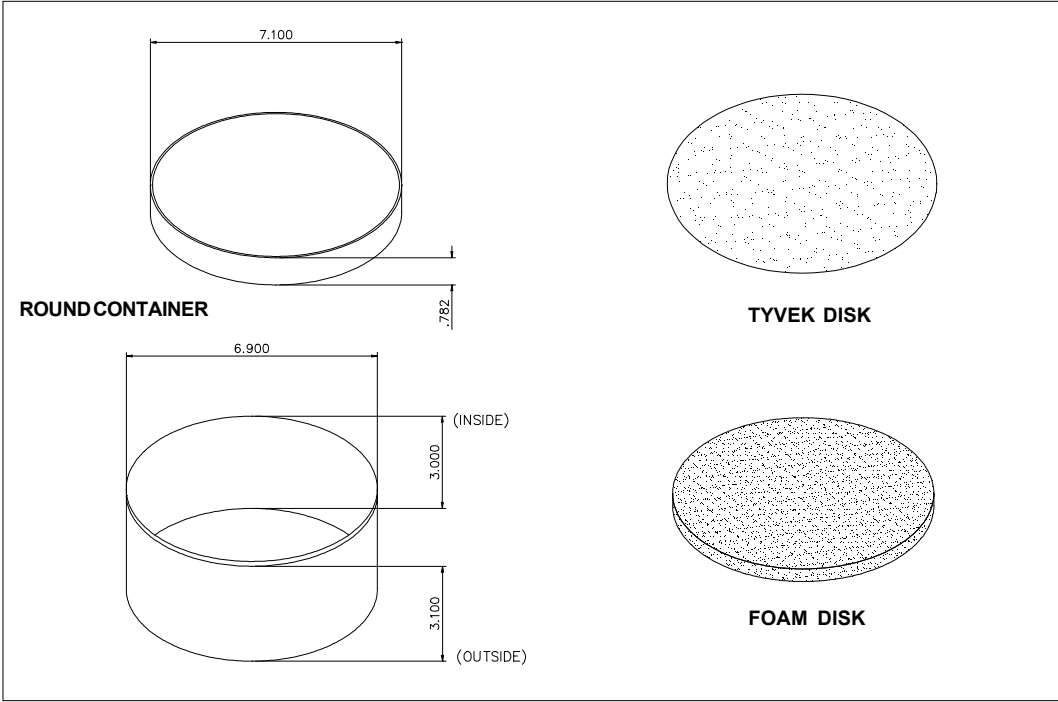
Device Code						
SC	200	S	100	A	5	B
1	2	3	4	5	6	7
1	- Schottky Die					
2	- Chip Dimension in Mils					
3	- Process (see Electrical Characteristics Table)					
4	- Voltage code: Code = V_{RRM}					
5	- Chip surface metallization (see Mechanical Data Table)					
6	- Wafer Diameter in inches					
7	- Packaging (see Packaging Table)					

H = 830 Process
R = OR'ing Process
S = Standard Process

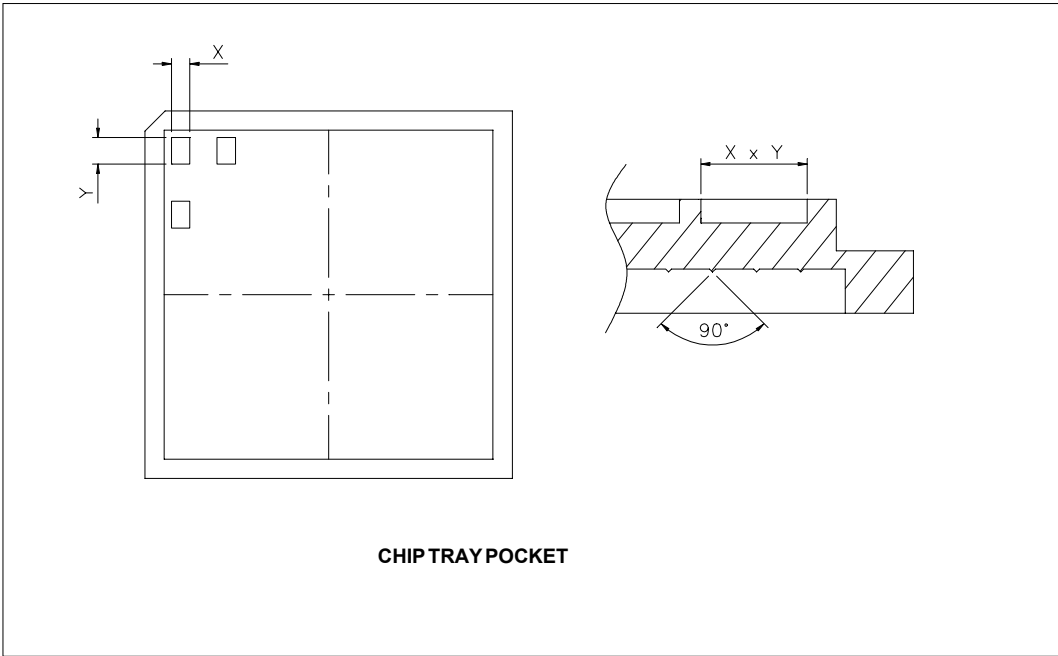
Wafer on Film



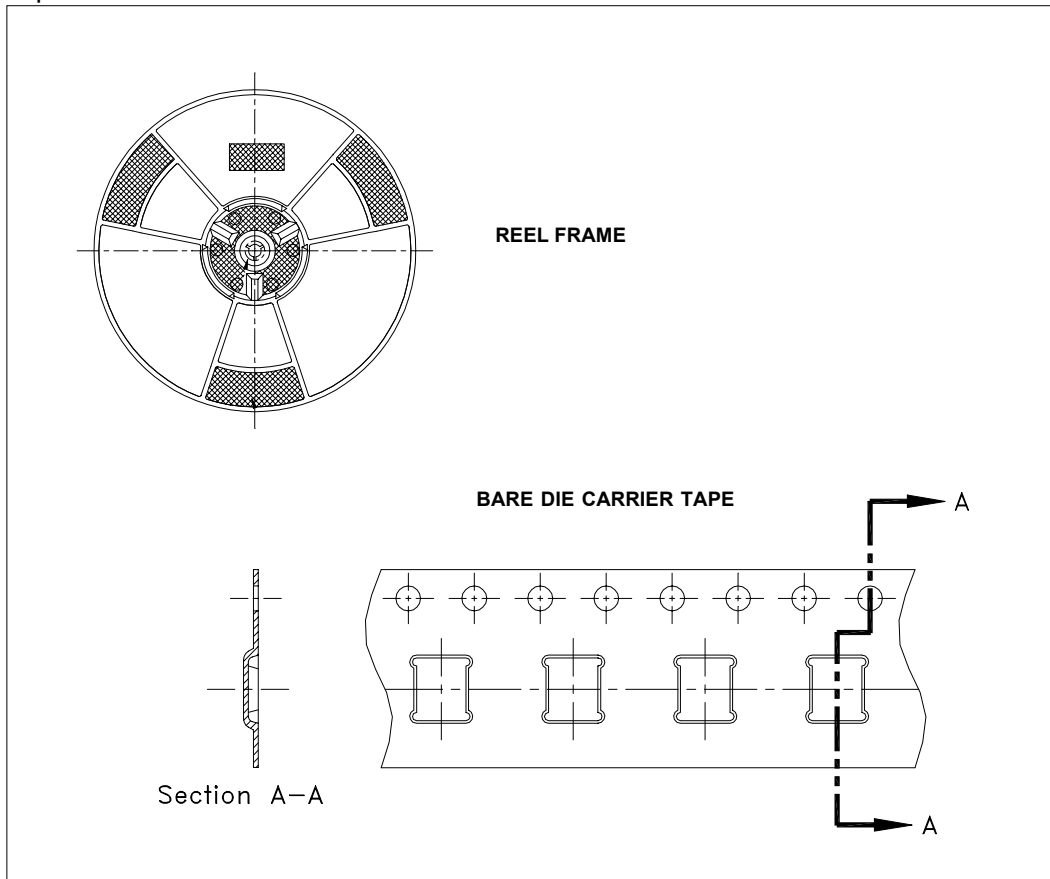
Wafer in Box



Die in Waffle Pack



Tape and Reel



International
IR Rectifier

WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245 U.S.A. Tel: (310) 322 3331. Fax: (310) 322 3332.
EUROPEAN HEADQUARTERS: Hurst Green, Oxted, Surrey RH8 9BB, U.K. Tel: ++ 44 1883 732020. Fax: ++ 44 1883 733408.
IR CANADA: 15 Lincoln Court, Brampton, Markham, Ontario L6T3Z2. Tel: (905) 453 2200. Fax: (905) 475 8801.
IR GERMANY: Saalburgstrasse 157, 61350 Bad Homburg. Tel: ++ 49 6172 96590. Fax: ++ 49 6172 965933.
IR ITALY: Via Liguria 49, 10071 Borgaro, Torino. Tel: ++ 39 11 4510111. Fax: ++ 39 11 4510220.
IR FAR EAST: K&H Bldg., 2F, 30-4 Nishi-Ikebukuro 3-Chome, Toshima-Ku, Tokyo, Japan 171. Tel: 81 3 3983 0086.
IR SOUTHEAST ASIA: 1 Kim Seng Promenade, Great World City West Tower, 13-11, Singapore 237994. Tel: ++ 65 838 4630.
IR TAIWAN: 16 Fl. Suite D.207, Sec. 2, Tun Haw South Road, Taipei, 10673, Taiwan. Tel: 886 2 2377 9936.

<http://www.irf.com>

Fax-On-Demand: +44 1883 733420

Data and specifications subject to change without notice.